

# Precision Low Dropout Linear Controllers

## FEATURES

- Precision 1% Reference
- Over-Current Sense Threshold Accurate to 5%
- Programmable Duty-Ratio Over-Current Protection
- 4.5 V to 36 V Operation
- 100mA Output Drive, Source, or Sink
- Under-Voltage Lockout

Additional Features of the UC2832 series:

- Adjustable Current Limit to Current Sense Ratio
- Separate +VIN terminal
- Programmable Driver Current Limit
- Access to VREF and E/A(+)
- Logic-Level Disable Input

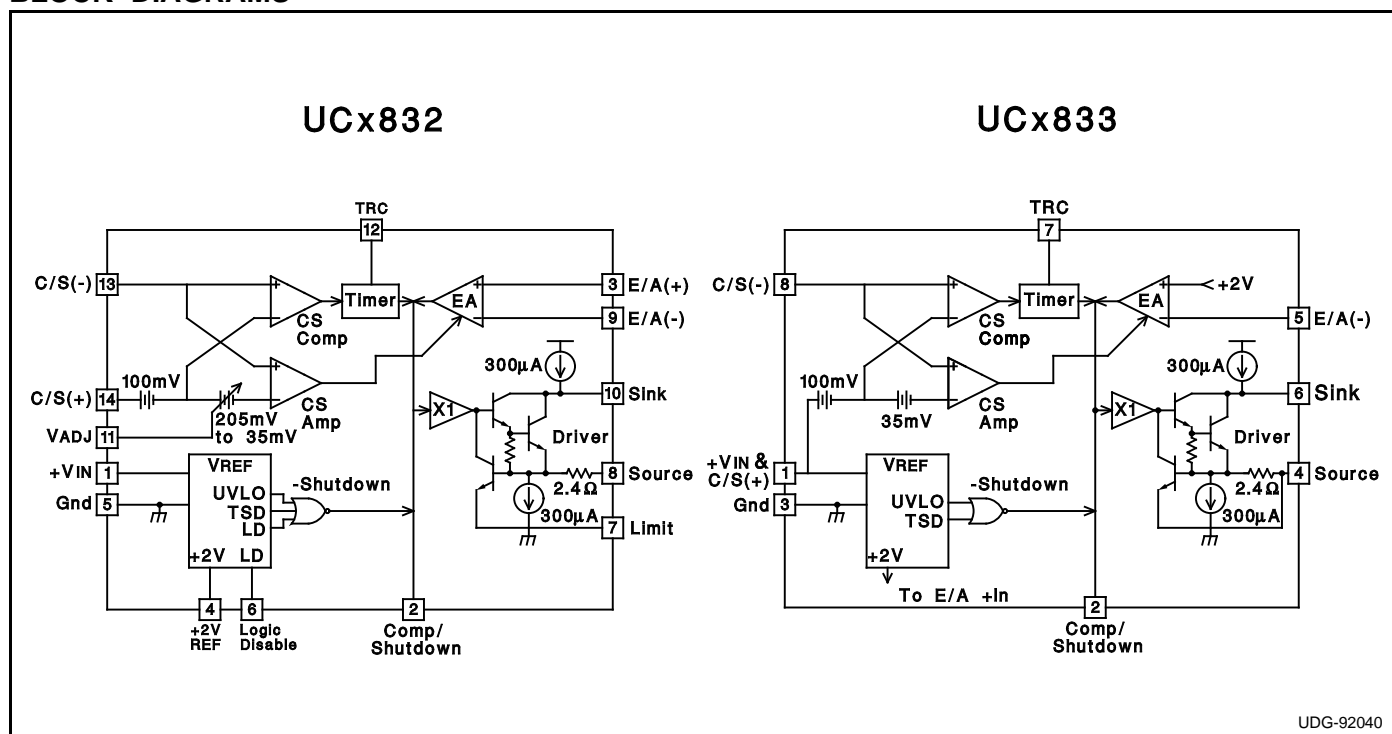
## DESCRIPTION

The UC2832 and UC3833 series of precision linear regulators include all the control functions required in the design of very low dropout linear regulators. Additionally, they feature an innovative duty-ratio current limiting technique which provides peak load capability while limiting the average power dissipation of the external pass transistor during fault conditions. When the load current reaches an accurately programmed threshold, a gated-astable timer is enabled, which switches the regulator's pass device off and on at an externally programmable duty-ratio. During the on-time of the pass element, the output current is limited to a value slightly higher than the trip threshold of the duty-ratio timer. The constant-current-limit is programmable on the UCx832 to allow higher peak current during the on-time of the pass device. With duty-ratio control, high initial load demands and short circuit protection may both be accommodated without extra heat sinking or foldback current limiting. Additionally, if the timer pin is grounded, the duty-ratio timer is disabled, and the IC operates in constant-voltage/constant-current regulating mode.

These IC's include a 2 Volt ( $\pm 1\%$ ) reference, error amplifier, UVLO, and a high current driver that has both source and sink outputs, allowing the use of either NPN or PNP external pass transistors. Safe operation is assured by the inclusion of under-voltage lockout (UVLO) and thermal shutdown.

The UC3833 family includes the basic functions of this design in a low-cost, 8-pin mini-dip package, while the UC2832 series provides added versatility with the availability of 14 pins. Packaging options include plastic (N suffix), or ceramic (J suffix). Specified operating temperature ranges are: commercial ( $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ ), order UC3832/3 (N or J); and industrial ( $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ ), order UC2832/3 (N or J). Surface mount packaging is also available.

## BLOCK DIAGRAMS



UDG-92040

### ABSOLUTE MAXIMUM RATINGS

Supply Voltage +VIN	40V
Driver Output Current (Sink or Source)	450mA
Driver Sink to Source Voltage	40V
TRC Pin Voltage	-0.3V to 3.2V
Other Input Voltages	-0.3V to +VIN
Operating Junction Temperature (note 2)	-55°C to +150°C
Storage Temperature	-65°C to +150°C
Lead Temperature (Soldering, 10 Seconds)	300°C

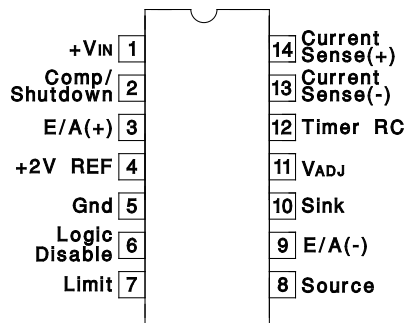
Note 1: Unless otherwise indicated, voltages are referenced to ground and currents are positive into, negative out of, the specified terminals.

Note 2: See Unitorde Integrated Circuits databook for information regarding thermal specifications and limitations of packages.

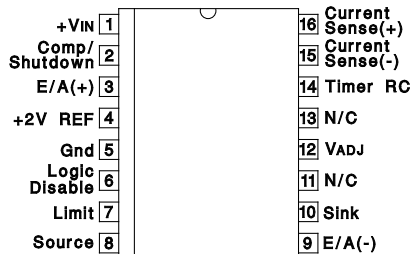
### CONNECTION DIAGRAMS

#### UC2832

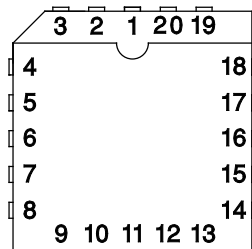
##### DIL-14 (Top View) J Or N Package



##### SOIC-16 (Top View) DW Package



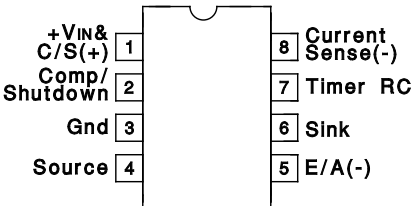
##### LCC-20 & PLCC-20 L & Q Package (Top View)



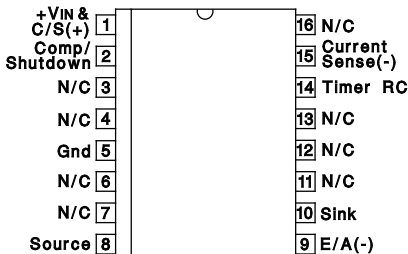
PACKAGE PIN FUNCTION	
FUNCTION	PIN
N/C	1
+VIN	2
Comp/Shutdown	3
E/A(+)	4
+2V REF	5
N/C	6
Gnd	7
Logic Disable	8
Limit	9
Source	10
N/C	11
E/A(-)	12
Sink	13
VADJ	14
N/C	15-17
Timer RC	18
Current Sense(-)	19
Current Sense(+)	20

#### UC3833

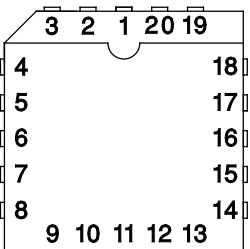
##### DIL-8 (Top View) J Or N Package



##### SOIC-16 (Top View) DW Package



##### LCC-20 & PLCC-20 L & Q Package (Top View)



PACKAGE PIN FUNCTION	
FUNCTION	PIN
+VIN & C/S(+)	1
N/C	2
N/C	3
N/C	4
Comp/Shutdown	5
Gnd	6
N/C	7
N/C	8
N/C	9
Source	10
N/C	11
E/A(-)	12
N/C	13
N/C	14
Sink	15
Timer RC	16
Current Sense(+)	17
N/C	18-20

**ELECTRICAL CHARACTERISTICS:** Unless otherwise stated, specifications hold for  
TA = 0°C to 70°C for the UC3832/3, -40°C to 85°C  
for the UC2832/3, +VIN = 15V, Driver sink = +VIN, C/S(+) voltage = +VIN. TA=TJ.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>Input Supply</b>					
Supply Current	+VIN = 6 V		6.5	10	mA
	+VIN = 36 V		9.5	15	mA
	Logic Disable = 2 V (UCx832 only)		3.3		mA
<b>Reference Section</b>					
Output Voltage (Note 3)	TJ = 25°C, IDRIVER = 10 mA	1.98	2.00	2.02	V
	over temperature, IDRIVER = 10 mA	1.96	2.00	2.04	V
Load Regulation (UCx832 only)	Io = 0 to 10 m	-10	-5.0		mV
Line Regulation	+VIN = 4.5 V to 36 V, IDRIVER = 10 m		0.033	0.5	mV/V
Under-Voltage Lockout Threshold			3.6	4.5	V
<b>Logic Disable Input (UCx832 only)</b>					
Threshold Voltage		1.3	1.4	1.5	V
Input Bias Current	Logic Disable = 0 V	-5.0	-1.0		μA
<b>Current Sense Section</b>					
Comparator Offset		95	100	105	mV
	Over Temperature	93	100	107	mV
Amplifier Offset (UCx833 only)		110	135	170	mV
Amplifier Offset (UCx832 only)	VADJ = Open	110	135	170	mV
	VADJ = 1 V	180	235	290	mV
	VADJ = 0 V	250	305	360	mV
Input Bias Current	VCM = +VIN	65	100	135	μA
Input Offset Current (UCx832 only)	VCM = +VIN	-10		10	μA
Amplifier CMRR (UCx832 only)	VCM = 4.1 V to +VIN + 0.3		80		dB
Transconductance	ICOMP = ±100 μA		6		mS
VADJ Input Current (UCx832 only)	VADJ = 0V	-10	-1		μA
<b>Timer</b>					
Inactive Leakage Current	C/S(+) = C/S(-) = +VIN; TRC pin = 2 V		0.25	1.0	μA
Active Pullup Current	C/S(+) = +VIN, C/S(-) = +VIN - 0.4V; TRC pin = 0 V	-345	-270	-175	μA
Duty Ratio (note 4)	ontime/period, RT = 200k, CT = 0.27μF		4.8		%
Period (notes 4,5)	ontime + offtime, RT = 200k, CT = 0.27μF		36		ms
Upper Trip Threshold (Vu)			1.8		V
Lower Trip Threshold (VI)			0.9		V
Trip Threshold Ratio	Vu/VI		2.0		V/V
<b>Error Amplifier</b>					
Input Offset Voltage (UCx832 only)	VCM = VCOMP = 2 V	-8.0		8.0	mV
Input Bias Current	VCM = VCOMP = 2 V	-4.5	-1.1		μA
Input Offset Current (UCx832 only)	VCM = VCOMP = 2 V	-1.5		1.5	μA
AVOL	VCOMP = 1 V to 13 V	50	70		dB
CMRR (UCx832 only)	VCM = 0V to +VIN - 3 V	60	80		dB
PSRR (UCx832 only)	VCM = 2 V, +VIN = 4.5 V to 36		90		dB
Transconductance	ICOMP = ±10 μA		43		mS
VOH	ICOMP = 0, Volts below +VIN		.95	1.3	V
VOL	ICOMP = 0		.45	0.7	V
IOH	VCOMP = 2 V	-700	-500	-100	μA

# **ELECTRICAL CHARACTERISTICS (cont.)**

Unless otherwise stated, specifications hold for  $T_A = 0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$  for the UC3832/3,  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  for the UC2832/3,  $V_{IN} = 15\text{ V}$ , Driver sink =  $+V_{IN}$ , C/S(+) voltage =  $+V_{IN}$ .  $T_A = T_J$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
<b>Error Amplifier (cont.)</b>					
IOL	$V_{COMP} = 2\text{ V}$ , C/S(-) = $+V_{IN}$	100	500	700	$\mu\text{A}$
	$V_{COMP} = 2\text{ V}$ , C/S(-) = $+V_{IN} - 0.4\text{ V}$	2	6		$\text{mA}$
<b>Driver</b>					
Maximum Current	Driver Limit & Source pins common; $T_J = 25^{\circ}\text{C}$	200	300	400	$\text{mA}$
	Over Temperature	100	300	450	$\text{mA}$
Limiting Voltage (UCx832 only)	Driver Limit to Source voltage at current limit, $I_{SOURCE} = -10\text{ mA}$ ; $T_J = 25^{\circ}\text{C}$ (Note 6)		.72		$\text{V}$
Internal Current Sense Resistance	$T_J = 25^{\circ}\text{C}$ (Note 6)		2.4		$\Omega$
Pull-Up Current at Driver Sink	Compensation/Shutdown = $0.4\text{ V}$ ; Driver Sink = $+V_{IN} - 1\text{ V}$	-800	-300	-100	$\mu\text{A}$
	Compensation/Shutdown = $0.4\text{ V}$ , $+V_{IN} = 36\text{ V}$ ; Driver Sink = $35\text{ V}$	-1000	-300	-75	$\mu\text{A}$
Pull-Down Current at Driver Source	Compensation/Shutdown = $0.4\text{ V}$ ; Driver Source = $1\text{ V}$	150	300	700	$\mu\text{A}$
Saturation Voltage Sink to Source	Driver Source = $0\text{ V}$ ; Driver Current = $100\text{ mA}$		1.5		$\text{V}$
Maximum Source Voltage	Driver Sink = $+V_{IN}$ , Driver Current = $100\text{ mA}$ Volts below $+V_{IN}$		3.0		$\text{V}$
UVLO Sink Leakage	$+V_{IN} = \text{C/S}(+) = \text{C/S}(-) = 2.5\text{ V}$ , Driver Sink = $15\text{ V}$ , Driver Source = $0\text{ V}$ , $T_A = 25^{\circ}\text{C}$		25		$\mu\text{A}$
Maximum Reverse Source Voltage	Compensation/Shutdown = $0\text{ V}$ ; $I_{SOURCE} = 100\text{ }\mu\text{A}$ , $+V_{IN} = 3\text{ V}$		1.6		$\text{V}$
Thermal Shutdown			160		$^{\circ}\text{C}$

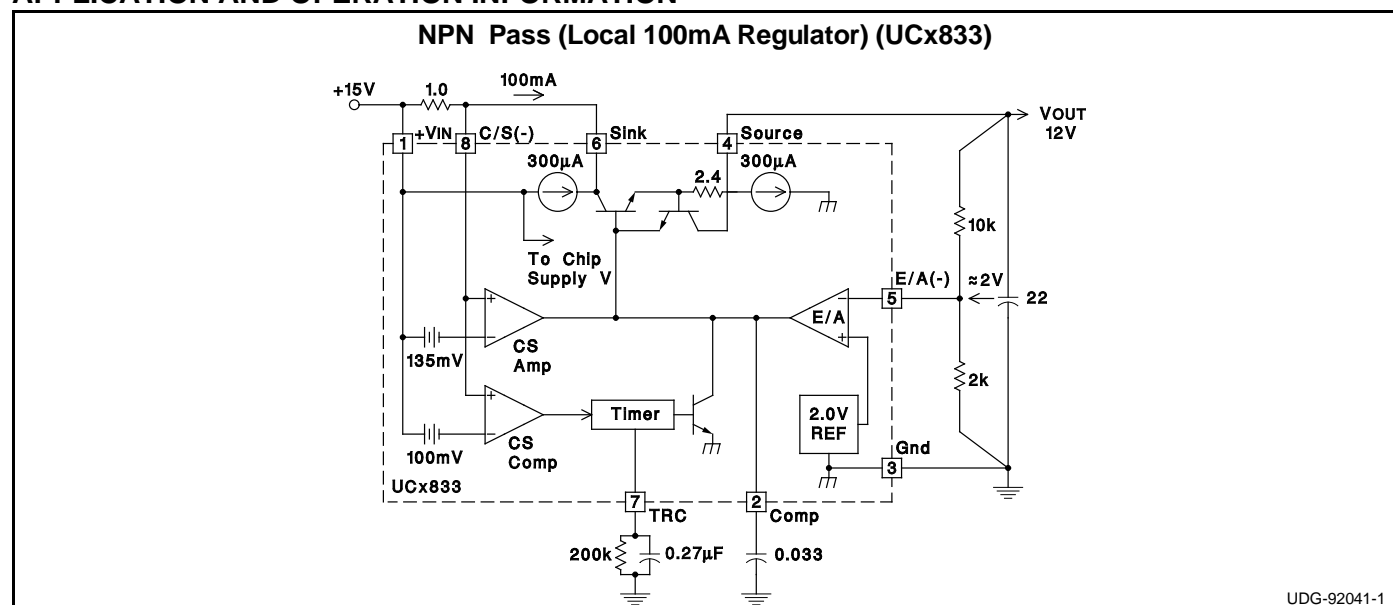
Note 3: On the UCx833 this voltage is defined as the regulating level at the error amplifier inverting input, with the error amplifier driving  $V_{SOURCE}$  to  $2\text{ V}$ .

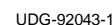
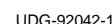
Note 4: These parameters are first-order supply-independent, however both may vary with supply for  $+V_{IN}$  less than about  $4\text{ V}$ . This supply variation will cause a slight change in the timer period and duty cycle, although a high off-time/on-time ratio will be maintained.

Note 5: With recommended  $R_T$  value of  $200\text{ k}$ ,  $T_{OFF} \approx R_T C_T \cdot \ln(V_u/V_l) \pm 10\%$ .

Note 6: The internal current limiting voltage has a temperature dependence of approximately  $-2.0\text{ mV}/^{\circ}\text{C}$ , or  $-2800\text{ ppm}/^{\circ}\text{C}$ . The internal  $2.4\text{ }\Omega$  sense resistor has a temperature dependence of approximately  $+1500\text{ ppm}/^{\circ}\text{C}$ .

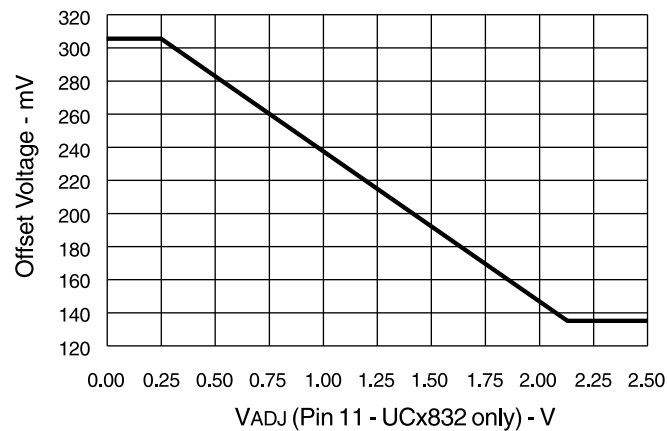
## **APPLICATION AND OPERATION INFORMATION**



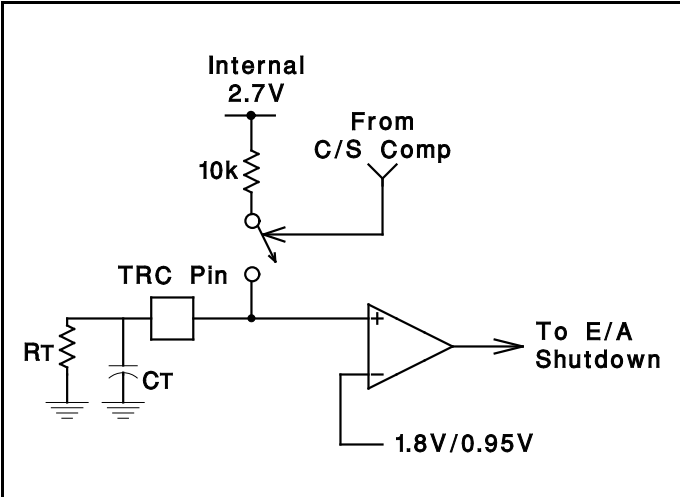

$$C_{MAX} = \frac{T_{ON}}{R_L} \bullet \frac{1}{\ln[(1 - \frac{V_{OUT}}{K \bullet I_{TH} \bullet R_I})^{-1}]}$$

# APPLICATION AND OPERATION INFORMATION (cont.)

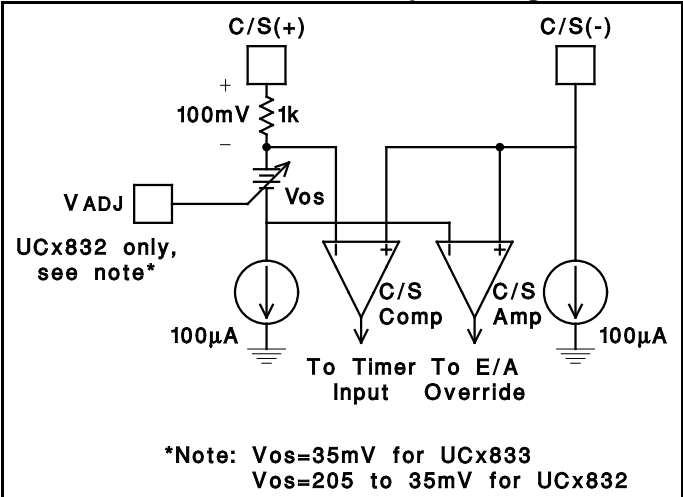
Current Sense Amplifier Offset Voltage vs V<sub>ADJ</sub>



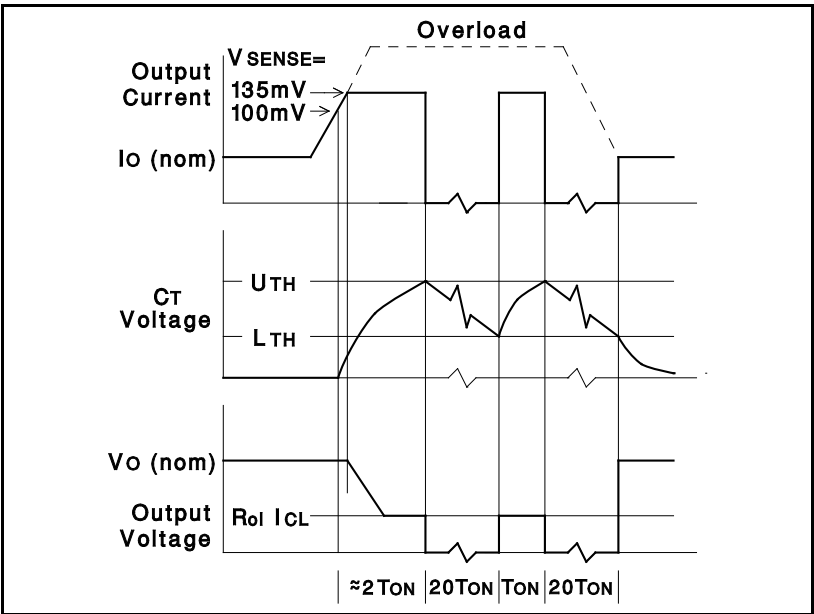
UCx832/33 Timer Function



UCx832/33 Current Sense Input Configuration



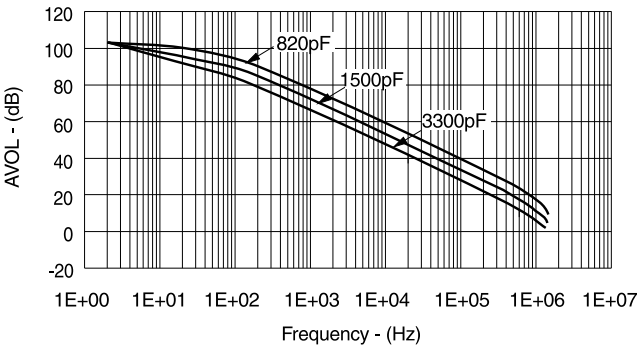
Load current, timing capacitor voltage, and output voltage of the regulator under fault conditions.



# APPLICATION AND OPERATION INFORMATION (cont.)

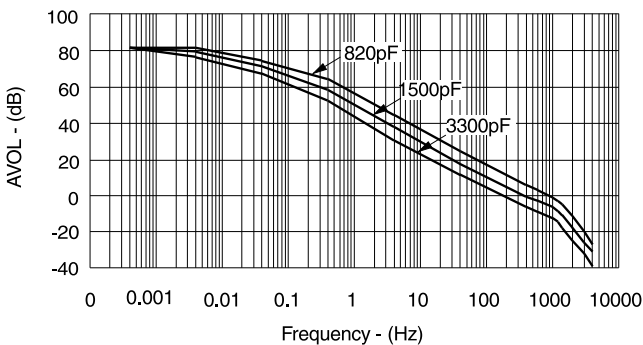
## UCx832 Error Amplifier

AVOL vs Frequency and CC



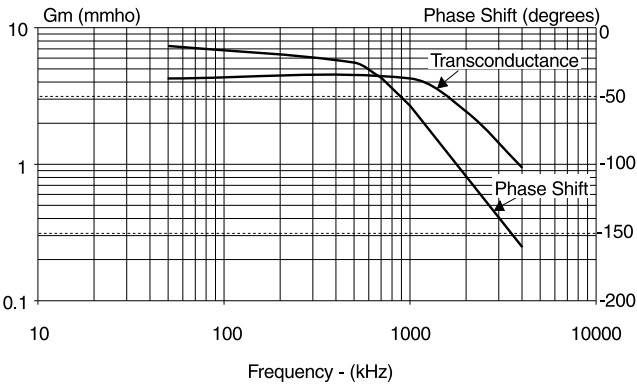
## UCx832 Current Sense Amplifier

AVOL vs Frequency and CC



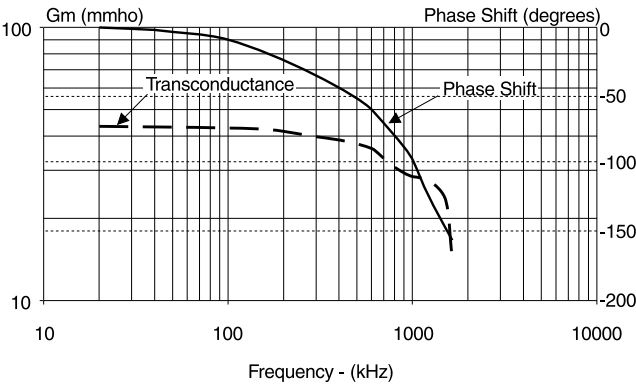
## UCx832 Error Amplifier

Transconductance and Phase vs Frequency



## UCx832 Current Sense Amplifier

Transconductance and Phase vs Frequency



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9326501M2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9326501M2A UC1832L/ 883B	<a href="#">Samples</a>
5962-9326501MCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9326501MC A UC1832J/883B	<a href="#">Samples</a>
5962-9326501V2A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9326501V2A UC1832L QMLV	<a href="#">Samples</a>
5962-9326501VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9326501VC A UC1832JQMLV	<a href="#">Samples</a>
UC1832J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	UC1832J	<a href="#">Samples</a>
UC1832J883B	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9326501MC A UC1832J/883B	<a href="#">Samples</a>
UC1832L883B	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9326501M2A UC1832L/ 883B	<a href="#">Samples</a>
UC2832DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-25 to 85	UC2832DW	<a href="#">Samples</a>
UC2833DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2833DW	<a href="#">Samples</a>
UC2833DWG4	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2833DW	<a href="#">Samples</a>
UC2833DWTR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2833DW	<a href="#">Samples</a>
UC3832DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3832DW	<a href="#">Samples</a>
UC3833DW	ACTIVE	SOIC	DW	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3833DW	<a href="#">Samples</a>
UC3833DWTR	ACTIVE	SOIC	DW	16	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UC3833DW	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of  $\leq 1000$ ppm threshold. Antimony trioxide based flame retardants must also meet the  $\leq 1000$ ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF UC1832, UC1832-SP, UC2832, UC3832 :**

● Catalog : [UC3832](#), [UC1832](#)

● Enhanced Product : [UC2832-EP](#)

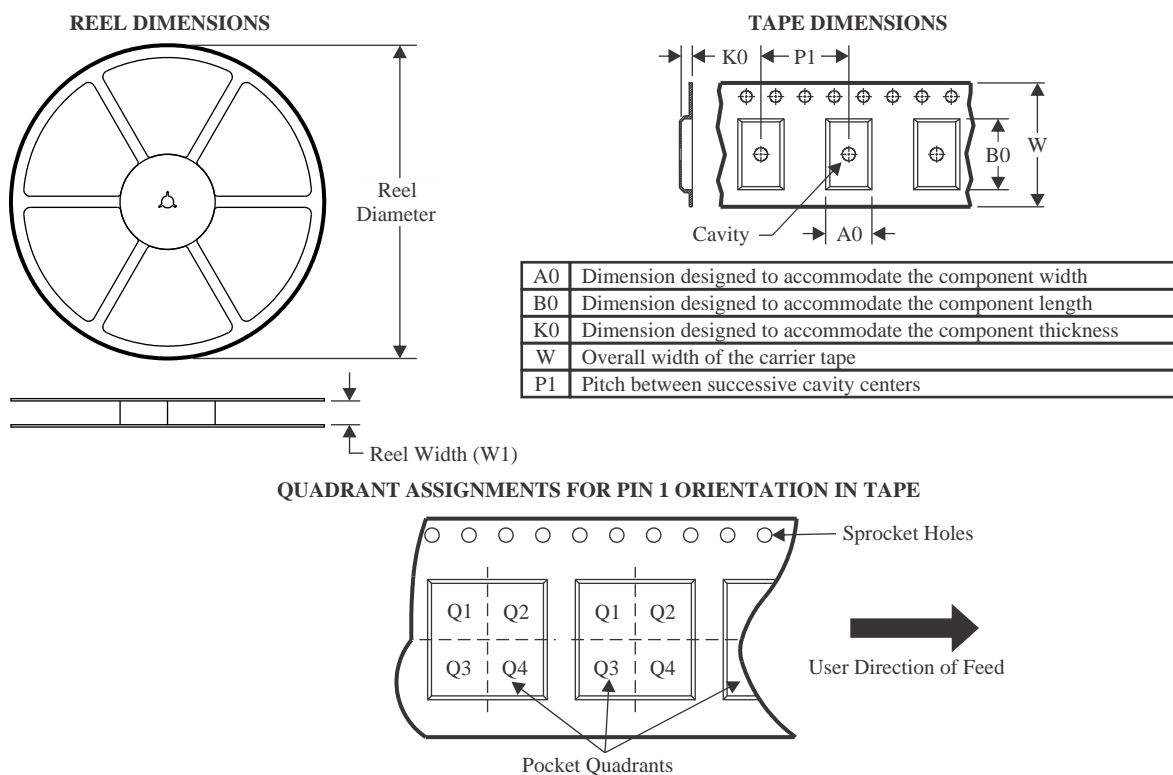
● Military : [UC1832](#)

- Space : [UC1832-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

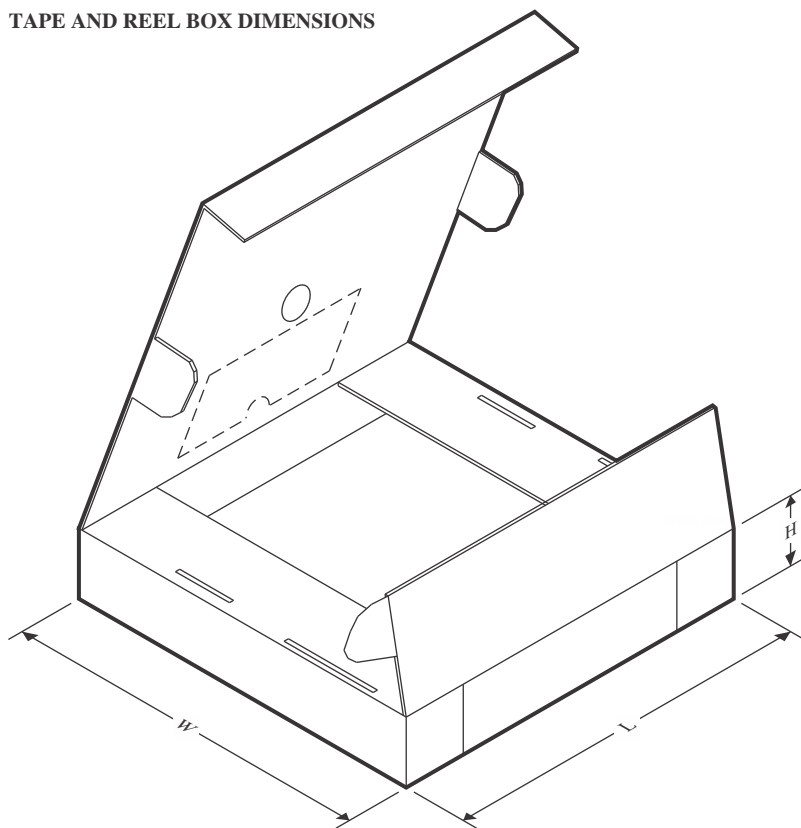
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2833DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
UC3833DWTR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

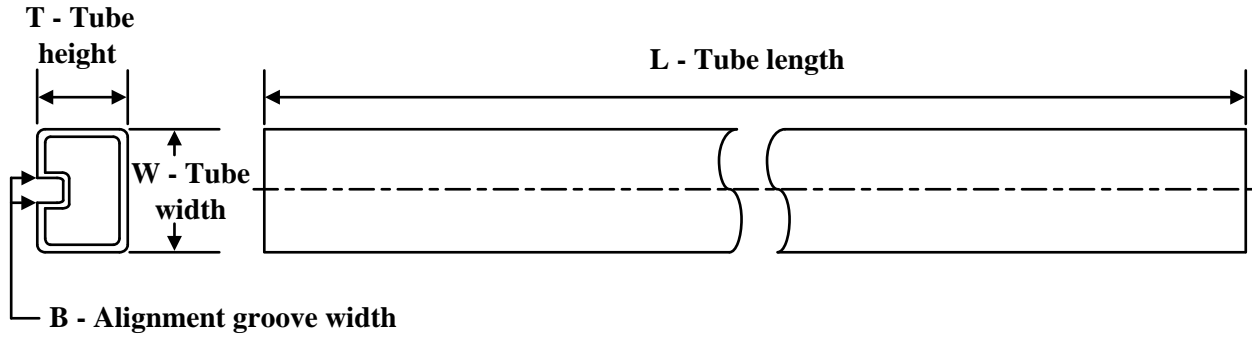
## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2833DWTR	SOIC	DW	16	2000	356.0	356.0	35.0
UC3833DWTR	SOIC	DW	16	2000	356.0	356.0	35.0

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9326501M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9326501V2A	FK	LCCC	20	55	506.98	12.06	2030	NA
UC1832L883B	FK	LCCC	20	55	506.98	12.06	2030	NA
UC2832DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC2833DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC2833DWG4	DW	SOIC	16	40	507	12.83	5080	6.6
UC3832DW	DW	SOIC	16	40	507	12.83	5080	6.6
UC3833DW	DW	SOIC	16	40	507	12.83	5080	6.6

## GENERIC PACKAGE VIEW

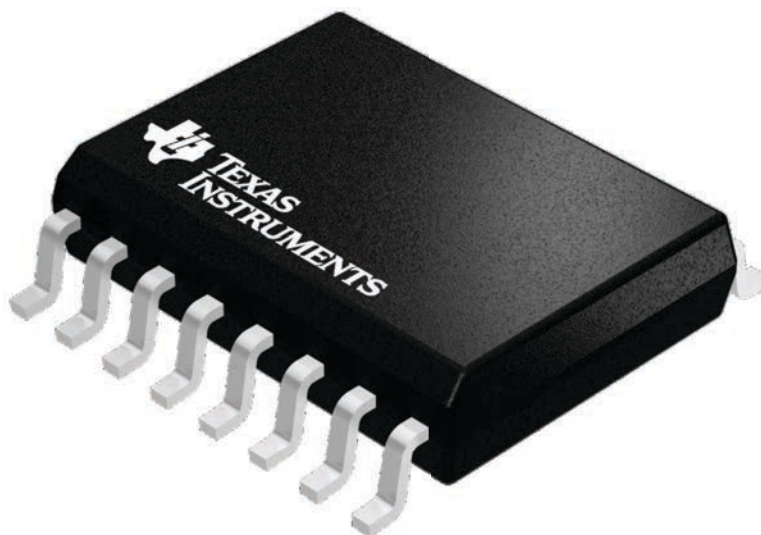
**DW 16**

**SOIC - 2.65 mm max height**

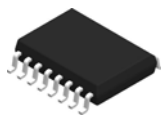
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4224780/A

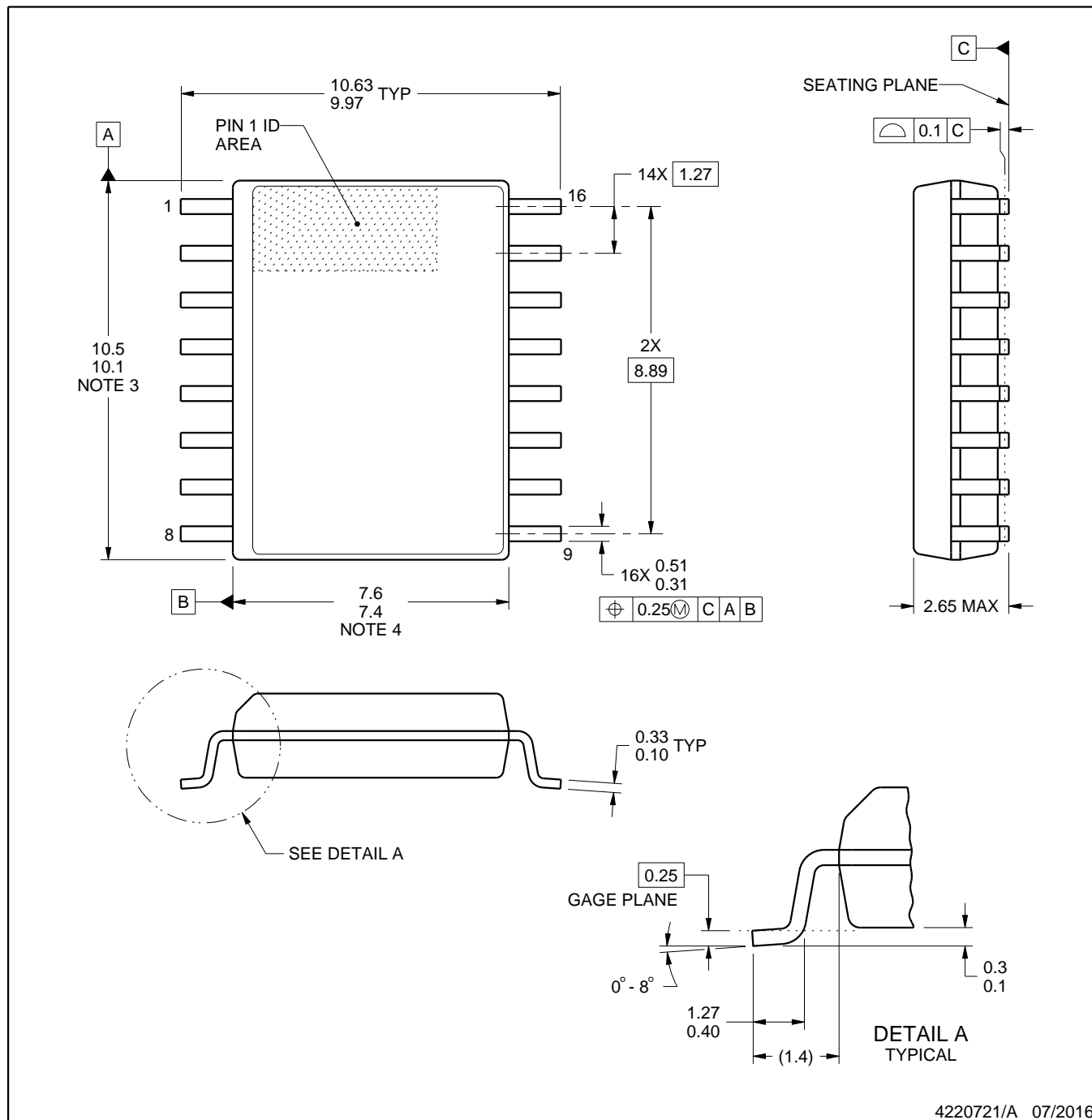


DW0016A

# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

### NOTES:

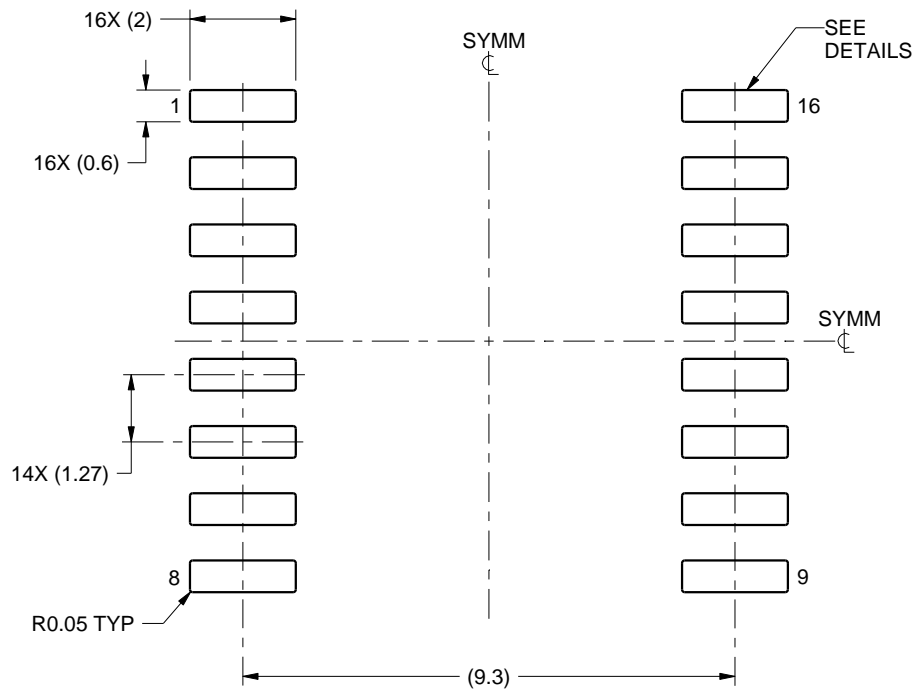
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

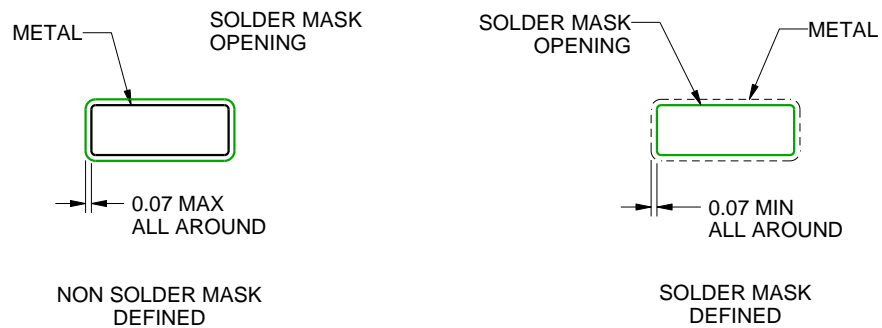
DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

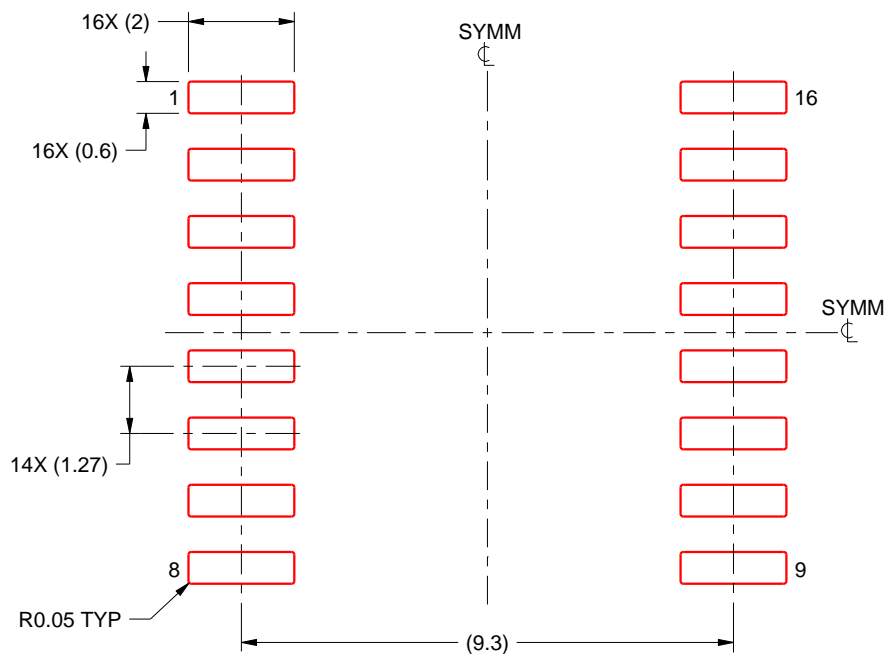
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

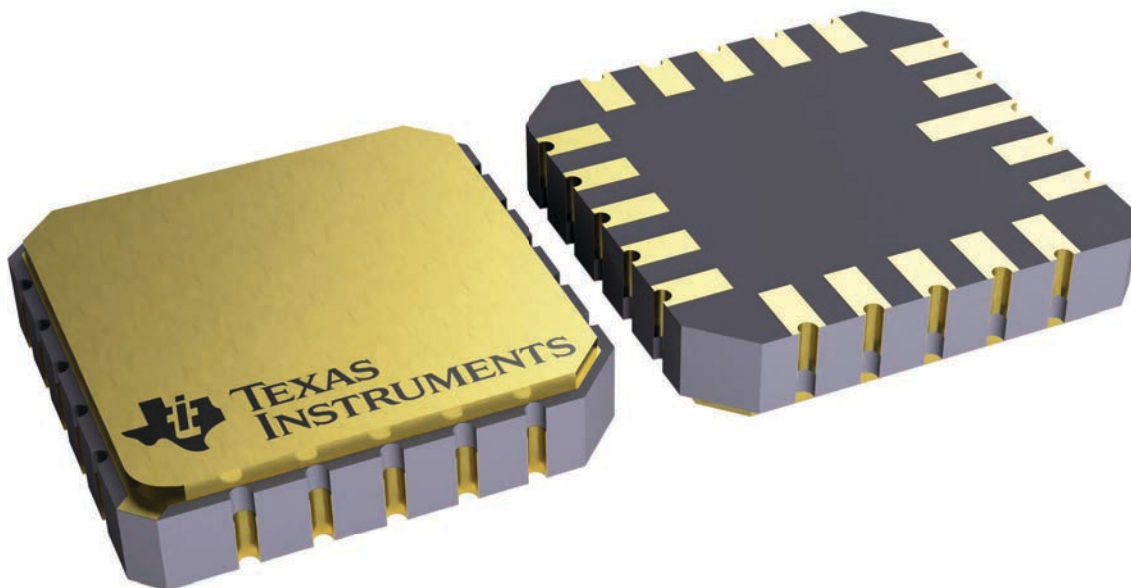
**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



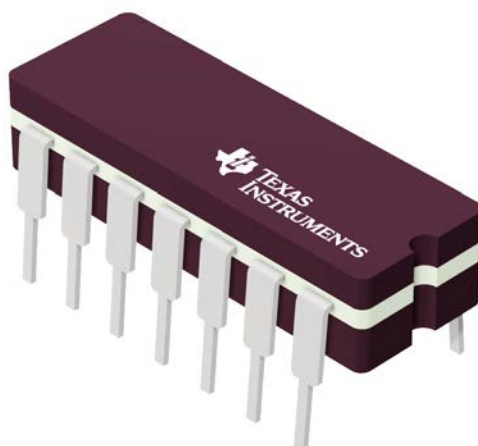
4229370VA\

**J 14**

## GENERIC PACKAGE VIEW

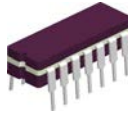
**CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE

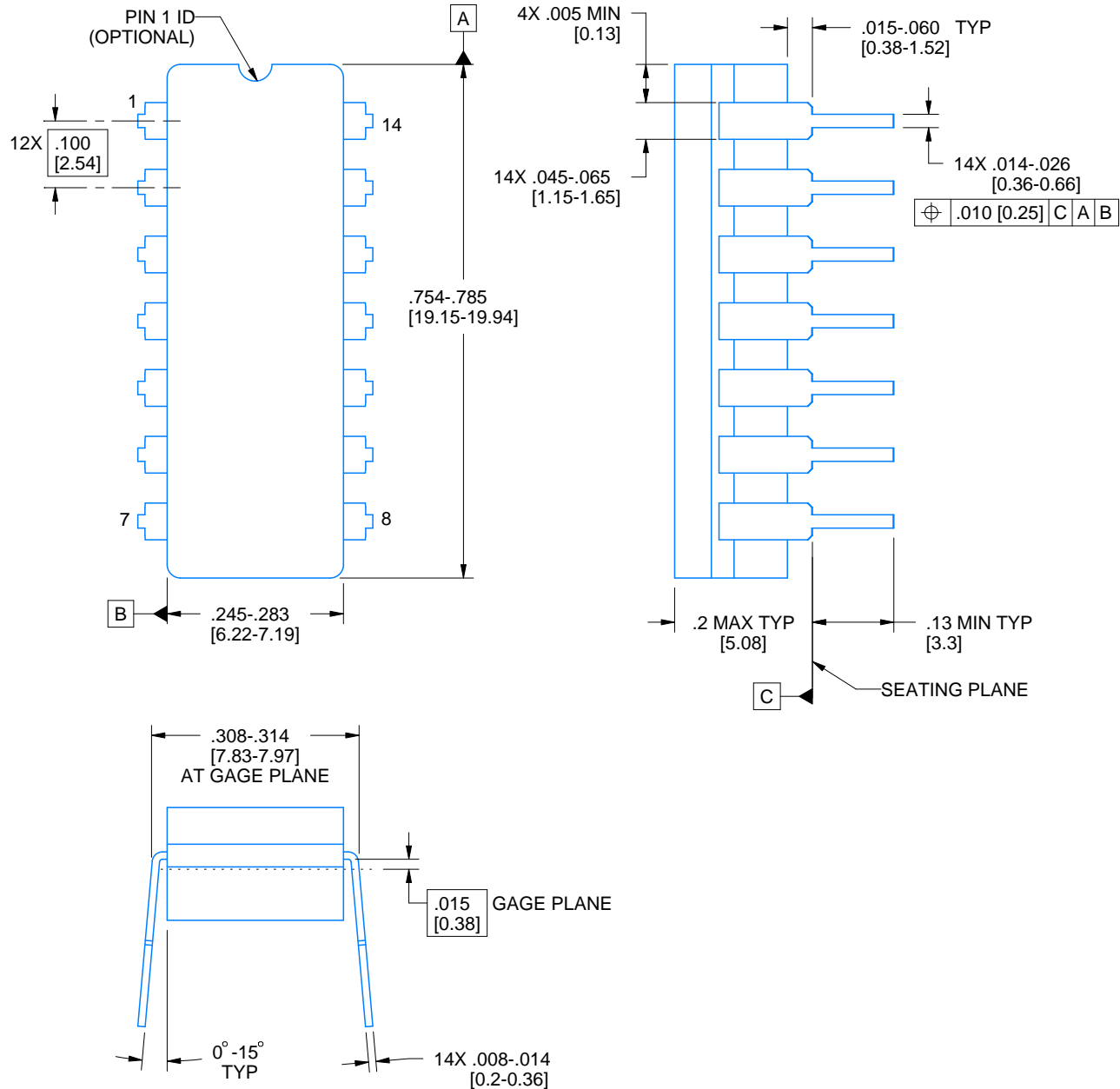


Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4040083-5/G

**J0014A****PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

**NOTES:**

1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.



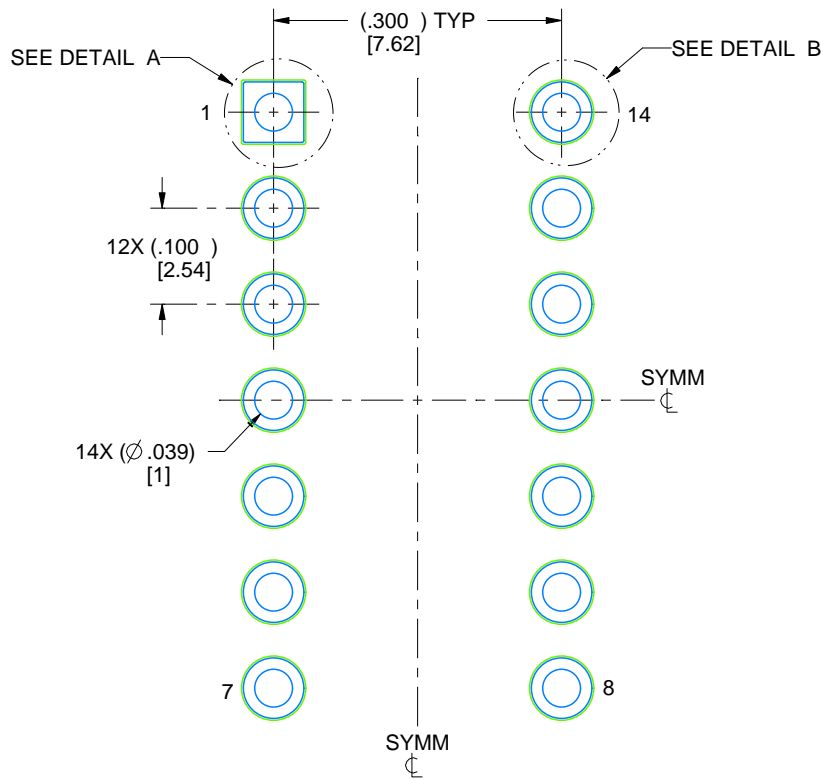
**TEXAS  
INSTRUMENTS**  
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# EXAMPLE BOARD LAYOUT

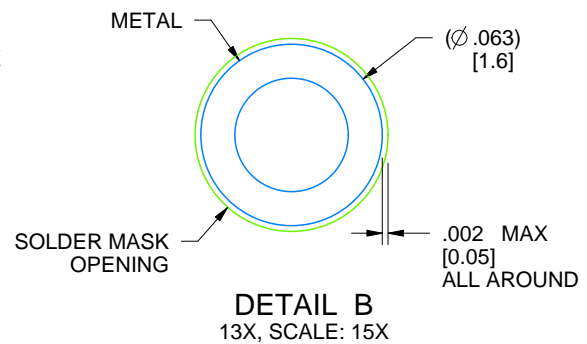
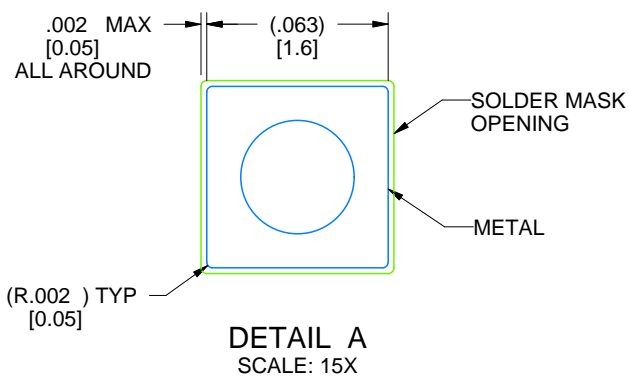
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE  
NON-SOLDER MASK DEFINED  
SCALE: 5X



4214771/A 05/2017

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